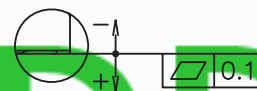
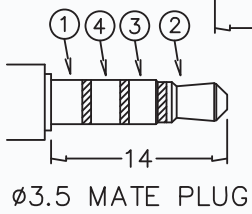
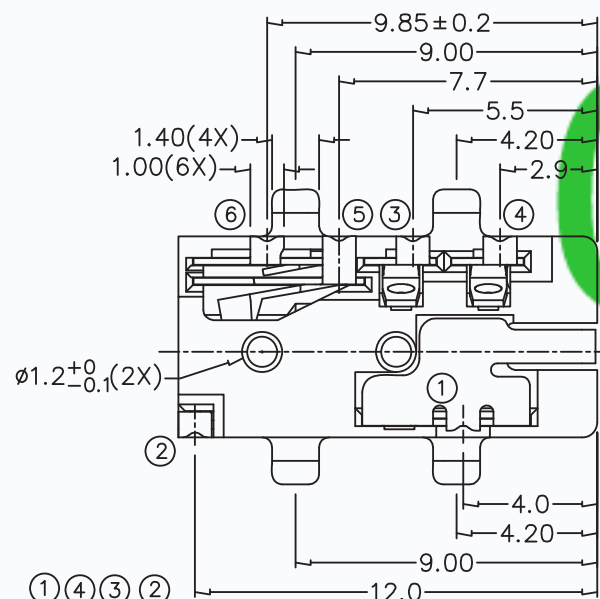
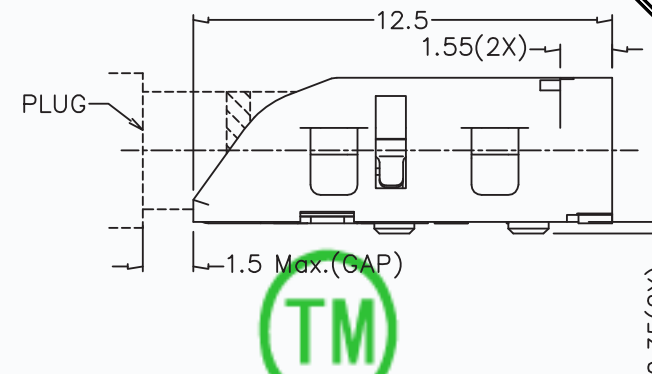
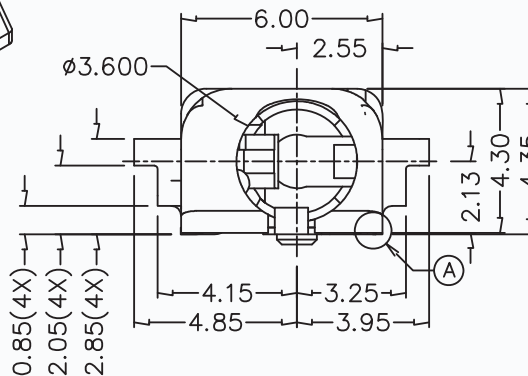
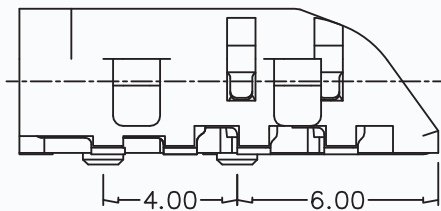
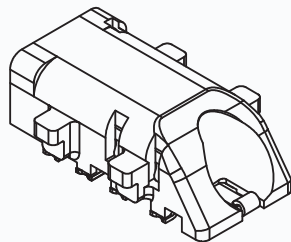
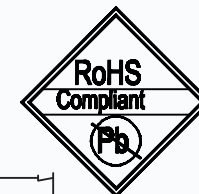


CAD FILE:

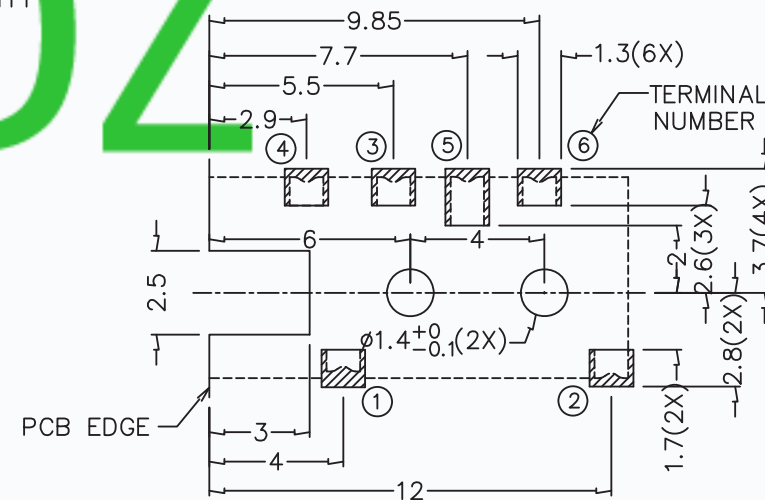


A DETAIL COPLANARITY

* MATERIAL

- TERMINAL 1 : COPPER ALLOY
- TERMINAL 2 : COPPER ALLOY
- TERMINAL 3 : COPPER ALLOY
- TERMINAL 4 : COPPER ALLOY
- TERMINAL 5 : COPPER ALLOY
- TERMINAL 6 : COPPER ALLOY
- HOUSING : PA10T
- INSULATOR : PA10T

MODEL NO.	T13-3575D
SCHEMATIC	



RECOMMENDED PCB LAYOUT
TOLERANCE: ±0.05
(TOP VIEW)

APPD.	DESCRIPTIONS OF REVISION

TOLERANCE
UNLESS SPECIFIED
WITHIN 1.5mm : ±0.1mm
OVER 1.5mm : ±0.2mm

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TITLE : 3.5mm PHONE JACK
MODEL: T13-3575D
CMTDDZ 东莞市田都电子有限公司
DONGGUAN TIANDU ELECTRONICS CO.,LTD.

UNIT : mm	DRWG NO.: CMTDDZ-T13-3575D-00
SCALE: 3:1	DWN. ERIC 2013-6-17
APPD. Coco	CHK'D MAIKO 2013-6-17
	APPD. Coco 2013-6-17